This **Sensor** is designed for nonintrusive measurement of the shear force on aerodynamic bodies.

qualitatively measure the shear force vector on aerodynamic bodies.

The sensors themselves are typically made in single crystal silicon with the piezoresistor elements formed by doping the silicon (by ion implantation or other means) to a suitable type and level of conductivity that provides the desired sensitivity depending on the crystal orientation. Metallic electrical leads on the back face of the device are provided to route excitation currents and output signal voltages from these sensors to the external world.

Subjecting the plate of the device to a shear force, by mounting it on an aerodynamic surface exposed to flow, will result in a moment acting on the hinges of the biaxial gimbal structure that is proportional to the shear stress on the plate, the arm, and torsional hinge dimensions. This moment creates a mechanical torsional shear stress within the hinges and, thereby, an output signal proportional to the shear stress on the plate from the piezoresistive sensor. The shear stress at the fluid-sensor interfaces is thus initially converted to a mechanical shear stress in the hinge that is sensed with a piezoresistive sensor. The two orthogonally located hinges and sensors enable measuring the shear stress existing on the plate in both directions. This configuration of the sensor device enables a large moment and stress level to be generated at the hinge from relatively small shear stress acting on a small plate, thereby enabling high spatial and stress resolution capability.

This work was done by Sateesh S. Bajikar of Goddard Space Flight Center and Michael A. Scott and Edward E. Adcock of Langley Research Center. Further information is contained in a TSP (see page 1). GSC-15431-1

Target Assembly to Check Boresight Alignment of Active Sensors

This assembly can simultaneously measure the co-boresite alignment of multiple transmitter laser beams and receiver channels.

Goddard Space Flight Center, Greenbelt, Maryland

A compact and portable target assembly (Fig. 1) has been developed to measure the boresite alignment of LRO's Lunar Orbiter Laser Altimeter (LOLA) instrument at the spacecraft level. The concept for this target assembly has evolved over many years with earlier versions used to test the Mars Observer Laser Altimeter (MOLA), the Geoscience Laser Altimeter System (GLAS), and the Mercury Laser Altimeter (MLA) space-based instruments. These earlier laser altimeters were single ranging channel instruments, but as demonstrated with the five-channel LOLA instrument, the target assembly can simultaneously measure the co-boresite alignment of multiple transmitter laser beams and receiver channels (Fig. 2).

The target assembly flips the transmitter laser beam into the optical receiver aperture and measures their co-alignment error by scanning the laser far-field image across the receiver field-of-view (FOV) in two orthogonal axes. Plotting the receiver response as a function of the transmitter beam deviation angle yields the effective laser altimeter transceiver alignment. The target assembly components include a Laser Beam Dump (LBD) to attenuate the input laser energy by an order of magnitude, a lateral transfer retro-re-
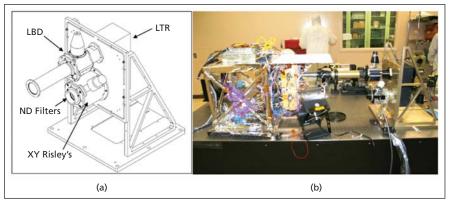

Fig. 1. **Target Assembly**: (a) LOLA target assembly components, (b) LOLA instrument test with target assembly.
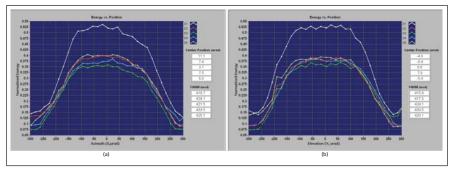
Fig. 2. **LOLA Laser 1 S/C Level Boresite Alignment Test Results**: (a) X-Axis, (b) Y-Axis.

flector (LTR) to flip the transmitter laser beam by exactly 180° into the receiver telescope, a set of motorized and computer-controlled Risley prisms to scan the transmitter laser beam across the receiver FOV in a controlled and measurable fashion, and a set of parallel plate neutral density (ND) fil-

ters to attenuate the output laser beam by several orders of magnitude to a receiver-safe level.

The target assembly is compact, modular, accurate, and easy to use. The target assembly itself is alignment insensitive, so no special care needs to be taken in placing the target assembly

in front of the instrument under test other than making sure that the transmitter laser beam is not vignetted at the target assembly entrance aperture. In addition, sealing the transmitter path to the target assembly input aperture is usually required to prevent stray light from saturating or damaging the sensitive receiver detector(s) of the instrument under test. The target assembly components can be easily changed to customize the target assembly for any required active sensor co-alignment measurement task.

Virtual Sensor Test Instrumentation

This technology has application in wireless RFID systems.

Stennis Space Center, Mississippi

Virtual Sensor Test Instrumentation is based on the concept of smart sensor technology for testing with intelligence needed to perform sell-diagnosis of health, and to participate in a hierarchy of health determination at sensor, process, and system levels. A virtual sensor test instrumentation consists of five elements: (1) a common sensor interface, (2) microprocessor, (3) wireless interface, (4) signal conditioning and ADC/DAC (analog-to-digital conversion/digital-to-analog conversion), and (5) onboard EEPROM (electrically erasable programmable read-only memory) for metadata storage and executable software to create powerful, scalable, reconfigurable, and reliable embedded and distributed test instruments. In order to maximize the efficient data conversion through the smart sensor node, plug-and-play functionality is required to interface with traditional sensors to enhance their identity and capabilities for data processing and communications.

Virtual sensor test instrumentation can be accessible wirelessly via a Network Capable Application Processor (NCAP)

or a Smart Transducer Interlace Module (STIM) that may be managed under real-time rule engines for mission-critical applications.

The transducer senses the physical quantity being measured and converts it into an electrical signal. The signal is fed to an A/D converter, and is ready for use by the processor to execute functional transformation based on the sensor characteristics stored in a Transducer Electronic Data Sheet (TEDS). Virtual sensor test instrumentation is built upon an open-system architecture with standardized protocol modules/stacks to interface with industry standards and commonly used software. One major benefit for deploying the virtual sensor test instrumentation is the ability, through a plug-and-play common interface, to convert raw sensor data in either analog or digital form, to an IEEE 1451 standard-based smart sensor, which has instructions to program sensors for a wide variety of functions. The sensor data is processed in a distributed fashion across the network, providing a large pool of resources in real time to meet stringent latency requirements. Advantages of de-

ploying the virtual sensor test instrumentation include:

- Simplification of troubleshooting through HTML/XML-based Health Monitoring that allows the user to verify all sensors via a graphic user interface.
- Cost reduction for set-up and tear-down through sensor auto detection.
- Elimination of recalibration when replacing sensors. The data acquisition system can recalibrate itself through TEDS.
- Elimination of large lengths of analog wiring through a radio frequency module.
- Reduction of installation, maintenance, and upgrade costs of measurement and control systems through Web-based TEDS server.
- Increased opportunity to add intelligence to sensors through embedded EEPROM.